



Science and  
Technology  
Facilities Council

# BCP Technology Transfer to Industry in the Framework of ESS

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On behalf of the STFC ESS  
team

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- BCP Requirements
- BCP Specification
- Validation Process
- Cavity Testing
- NCRs
- Summary



# BCP Requirement

- STFC agreed programme scope of work did not include any process developmental work
    - Plan to transfer processes from CEA Saclay to industry
  - BCP process developed and defined by CEA from prototypes and INFN medium beta cavity
  - Identified by STFC, ESS & CEA that industry process will be different to CEA process
    - Different set-up
    - Different acid concentration
- ⇒ Requirement to validate the BCP process with pre-series cavities prior to the commencement of the production cavities
- Bulk BCP required to remove 180  $\mu\text{m}$  from the cavity inner surface + 20  $\mu\text{m}$  light etch
  - Process:-
    - Perform initial treatments on cavity H001, then cold RF test undressed
    - Iterate the processes if required on cavity H002 (and H003, and H004)
    - In parallel forming of half-cells and fabrication of dumbbells for series production was progressed

# BCP Specification

1

- Frame assembly, cleaned and rinsed with hand-held pressure washer and moved into the ISO 7 (or better) cleanroom

2

- Degreasing and ultrasonic cleaning
- Ultra Pure Water (UPW) rinse - Resistivity > 12 MΩ.cm

3

- Drying in cleanroom ISO 7

4

- Weighed with the frame to enable the average surface removal obtained with chemistry

5

- Assemble blanking flanges (ports and beam tube flanges including an etching control Nb sample at the coupler port)

6

- Leak test of the BCP plant, pressurizing it with UPW

7

- Etching in closed loop, Bulk BCP - 1<sup>st</sup> step. First etching step: 80 μm.

8

- Pre-rinse cavity inside BCP loop Prompt rinsing of the cavity within 120 s after acid process stops

9

- Disassemble flanges for BCP and assemble flanges for the rinsing up to resistivity > 12 MΩ.cm

10

- Outer ultrasonic cleaning and rinsing of the closed cavity to enter ISO 4 cleanroom for HPR

11

- Standard High Pressure Rinsing (HPR): 120 min

12

- Drying in cleanroom ISO 7 or higher.

# BCP Specification

13

- Cavity weighing with frame (assessment of mass of Nb removed)

14

- Flip the cavity orientation to guarantee etching uniformity

15

- Etching in closed loop, Bulk BCP- 2<sup>nd</sup> step. Second etching step: 100  $\mu\text{m}$

16

- Pre-rinse cavity inside BCP loop to Ph >5 to stop reaction

17

- Disassemble BCP flanges and assemble flanges for the rinsing up to resistivity > 12 M $\Omega$  cm

18

- Outer ultrasonic cleaning and rinsing of the closed cavity for entering the ISO 4 HPR area

19

- Standard High Pressure Rinsing (HPR) (120 min)

20

- Drying in cleanroom ISO 7 or better

21

- Cavity weighing with frame (assessment of removal)

22

- Cavity can exit the cleanroom

23

- Remove frame

24

- Frequency measurement of the 5 modes of the cavity

# Vendor Validation Process

- Original BCP process qualified for 1.3 GHz cavities (XFEL)
- System required modifications to integrate the larger volume cavity
- Need to understand the etch rate
  - Acid concentration: 1 volume part HF (40%), 1 volume part HNO<sub>3</sub> (65%) and 2 volume parts H<sub>3</sub>PO<sub>4</sub> (85%) - different to CEAs
- Verification of heat exchanger capability
  - Acid is typically pre-cooled down to 5 to 7 °C before commencing etch process
  - Process typically between 12 – 15 °C
  - Acid temperature maintained below 15 °C for the whole process time
- Acid flow 10 -20l/min
- Ensure proper circulation of the acid and avoidance of any trapping of gas bubbles
- Verification of heat exchanger capability
  - Acid is typically pre-cooled down to 5 to 7 °C before commencing etch process
  - Process typically between 12 – 15 °C
  - Acid temperature maintained below 15 °C for the whole process time
- Performance witnessed by Axel Matheisen (consultant)



- Consider repeat of H001 process or progress to 90 μm etch



- Review etch rate consider 2 x 45 μm or 90 μm etch



Cavity validation process

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Cavity validation process

# Review Criteria

Parameter	'Full' pass similar to prototype data	Limited pass but 'review' if:	'Fail' if:
2K $Q_0$ @ 1 MV/m	$>2 \times 10^{10}$	Review if $<2 \times 10^{10}$	No fail condition
2K $Q_0$ @ 19.9 MV/m	$>1.45 \times 10^{10}$	$5 \times 10^9 < Q_0 < 1.45 \times 10^{10}$	$<5 \times 10^9$
Max $E_{acc}$	$>19.9$ MV/m	$>19.9$ MV/m	$<19.9$ MV/m
Field emission / X-ray		If early on-set of X-ray, review	No fail condition
<b>Actions:</b>	Release all pre-series cavities to processing	<b>De-bug of cavity</b> <i>If root cause analysis suggests:</i> "Local" cavity problem: <ul style="list-style-type: none"> <li>- Release next cavity / cavities</li> <li>- Re-treatment of cavity</li> </ul> Process problem: <ul style="list-style-type: none"> <li>- Review processes and modify if required</li> </ul>	<b>De-bug of cavity</b> Review processes and modify if required Consider re-test of cavity before release of cavity / cavities

## High-beta data, RI prototypes

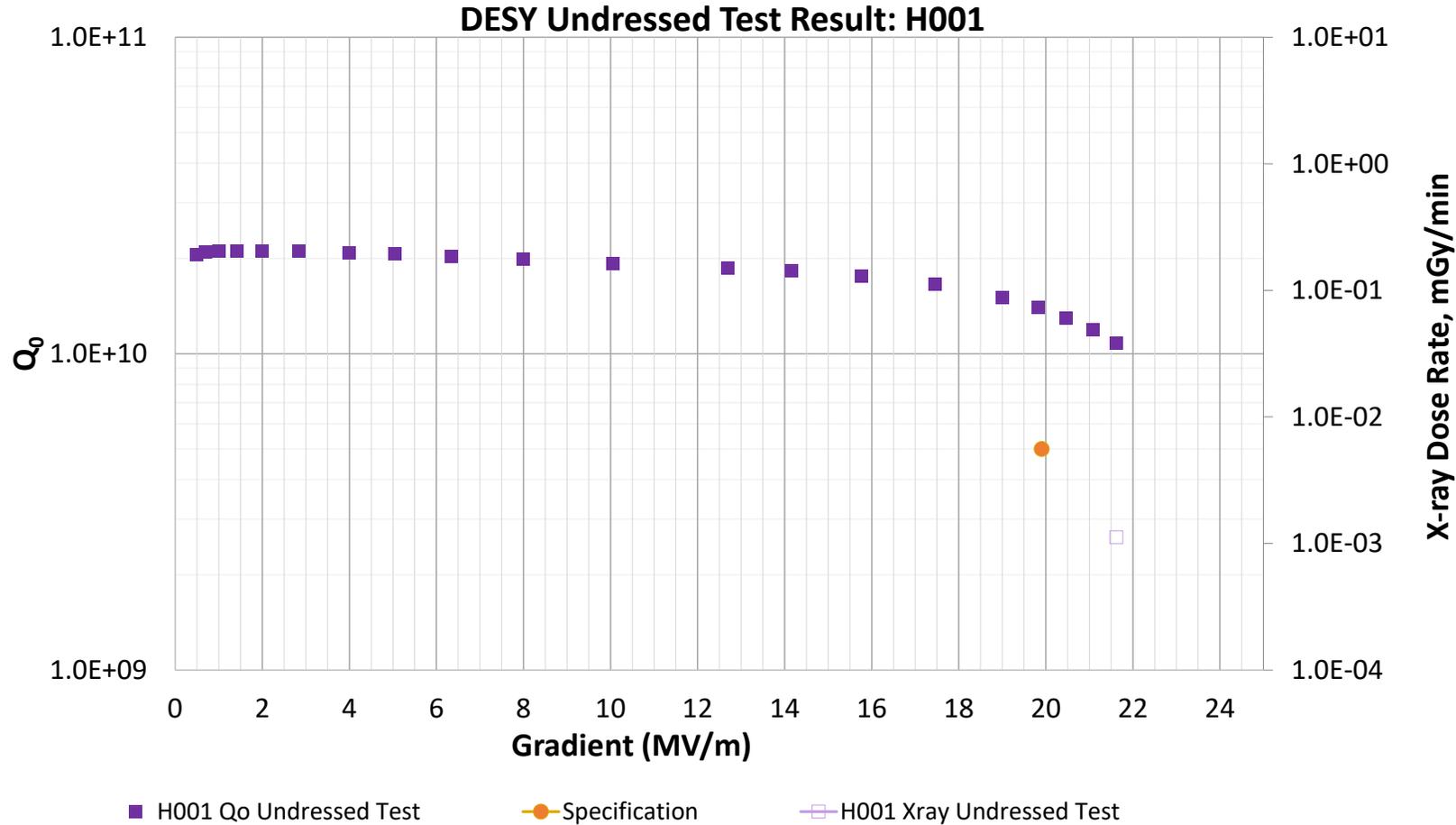
Cavity #	$Q_0$ @1MV/m	$Q_0$ @ 19.9MV/m	Max Eacc [MV/m]	$Q_0$ @Max Eacc
HB02T	2.50E+10	1.60E+10	22.7 (Power limited)	1.03E+10
HB04T	2.50E+10	1.90E+10	21.4 (Quench)	1.80E+10
HB05T	2.57E+10	1.90E+10	24.6 (Power limited)	1.20E+10

# De-bugging guide (Courtesy of Axel Matheisen)

Criteria		Assessment
<ul style="list-style-type: none"> <li>• <math>Q_0</math> low</li> <li>• No field emission</li> </ul>	First test	Check cavity for Q decrease during cold test
		Check mode spectrum during cold to identify if $Q_0$ is limited by a local problem
		Redo HPR and retest
	Still poor after retest	Optical inspection by camera
		Redo 20 $\mu\text{m}$ BCP with STFC people on place
<ul style="list-style-type: none"> <li>• <math>Q_0</math> ok</li> <li>• Limited by field emission</li> </ul>	First test	Check mode spectrum during cold to identify cell that limited by a local problem
		Redo HPR and retest
		Optical inspection by camera / check surface damages
	Still poor after retest	Grinding if needed
		Redo 20 $\mu\text{m}$ BCP with STFC people on place
<ul style="list-style-type: none"> <li>• <math>Q_0</math> ok</li> <li>• No field emission</li> <li>• Quench before specification limit</li> </ul>	First test	Check mode spectrum during cold to identify cell that limited by a local problem
		Install T sensors of cavity for localisation of defect
		Redo 20 $\mu\text{m}$ BCP and HPR
	Still poor after retest	Install T sensors of cavity for localisation of defect
		Optical inspection by camera
		Grinding if needed
		Redo 20 $\mu\text{m}$ BCP and HPR



# Undressed Pre-series Cavity Test: H001

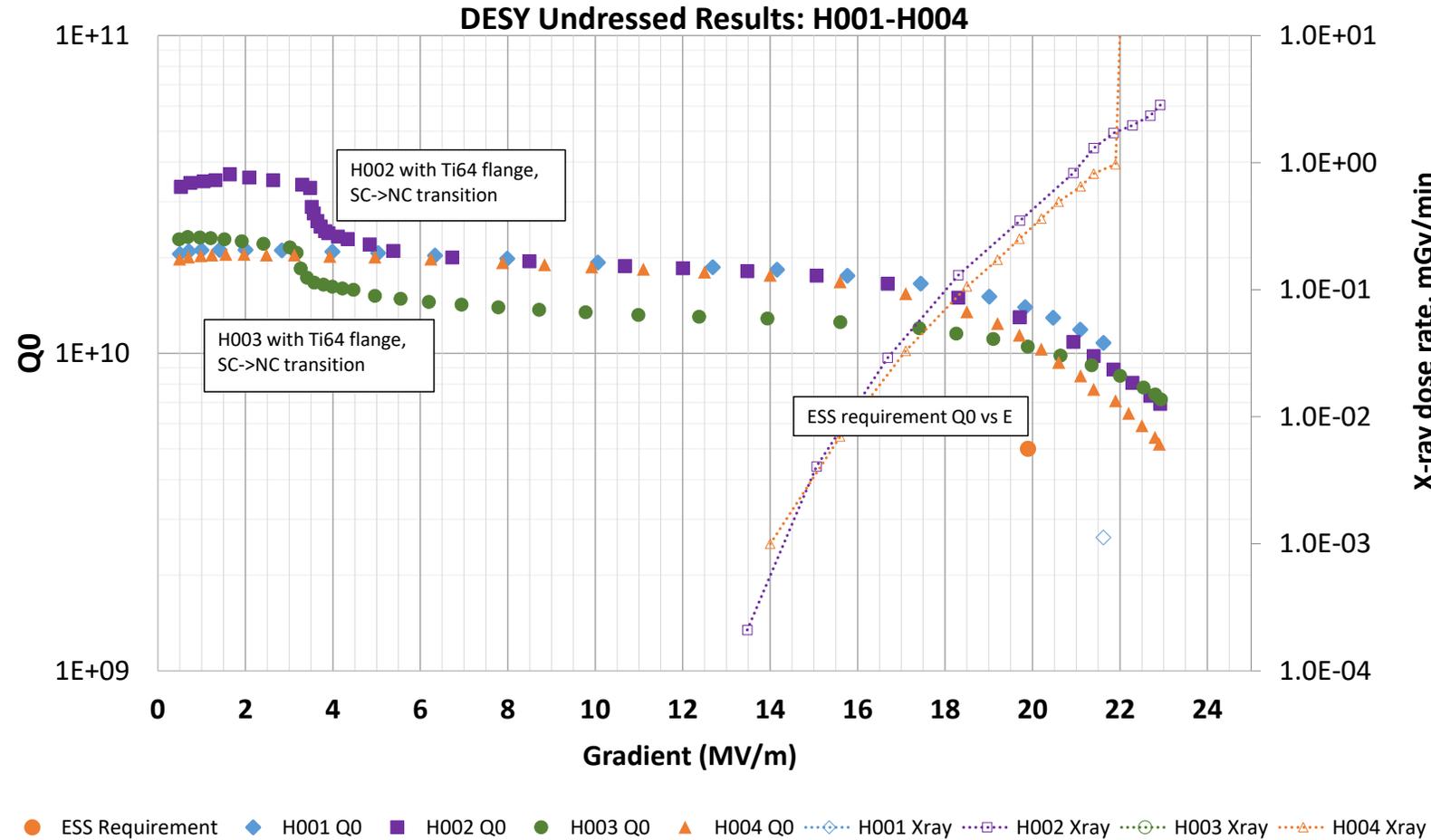


## Undressed Test

- Gradient and Q<sub>0</sub> specification achieved
  - Radiation observed above 21 MV/m
  - Criteria met
- ⇒ H002 released for processing



# Undressed Pre-series Cavity Tests



## H002, H003, and H004:

- Gradient and  $Q_0$  specification achieved
- H002 radiation observed
  - Cause identified to be incorrect seating when undergoing HPR
- H003 no radiation observed
- H004 radiation observed
- Criteria met

⇒ Process released for production cavities

# Non-Conformance Reports

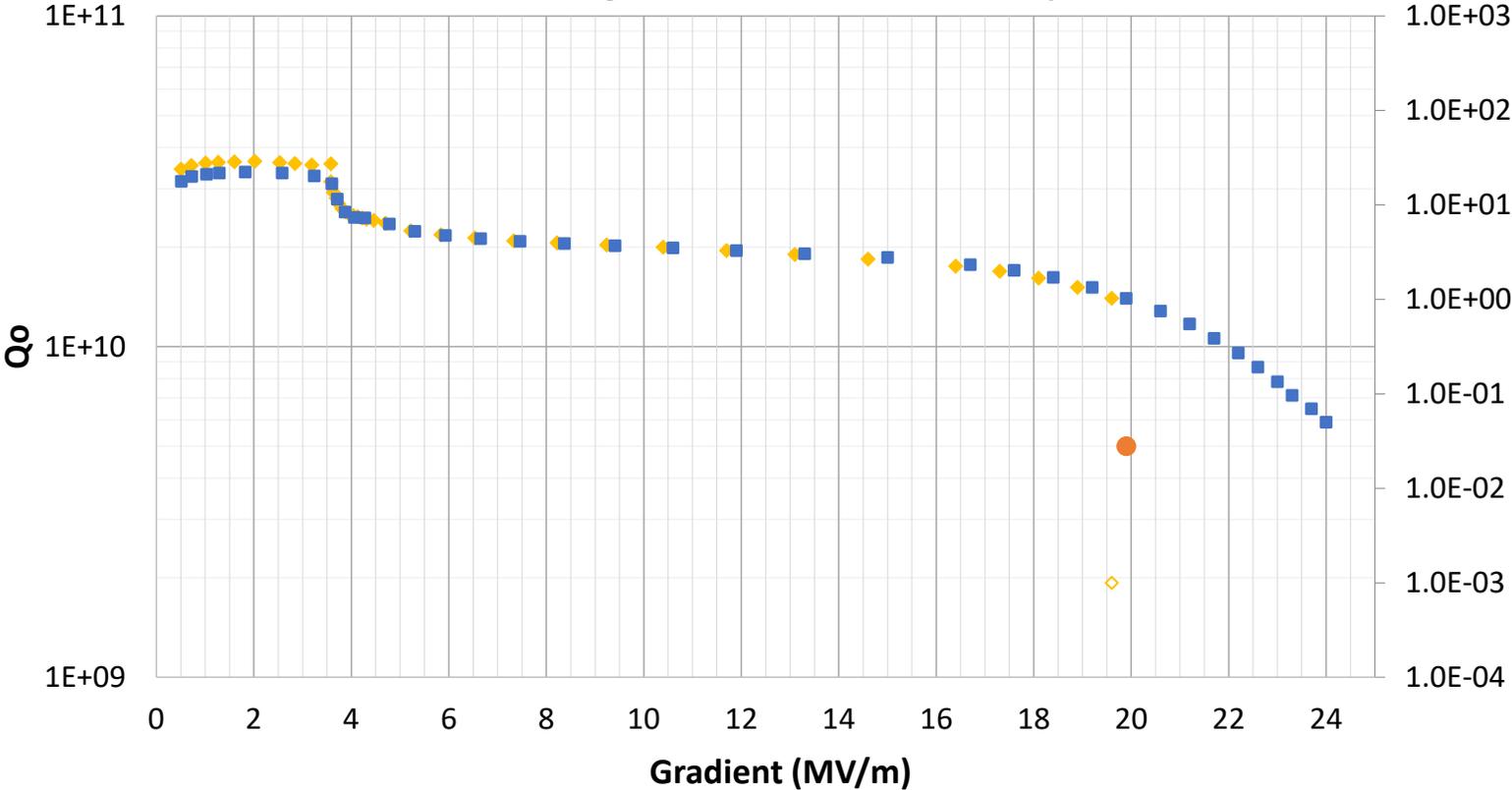
- Production cavity issues:-
  - Water resistivity too low on 4 cavities (Between 12 – 13 MΩ.cm)
  - Acid temperature exceeded 15 °C on 7 cavities
    - Issue occurred in the Summer and has improved
    - Maximum allowed increased to 16 °C, but the target is still 15 °C
  - Acid drain time was exceeded on 2-3 cavities
    - Reviewed valve opening operation

⇒ Monitoring continuing



# Dressed Production Cavity Tests

### DESY ESS High-Beta Dressed Cavity Results



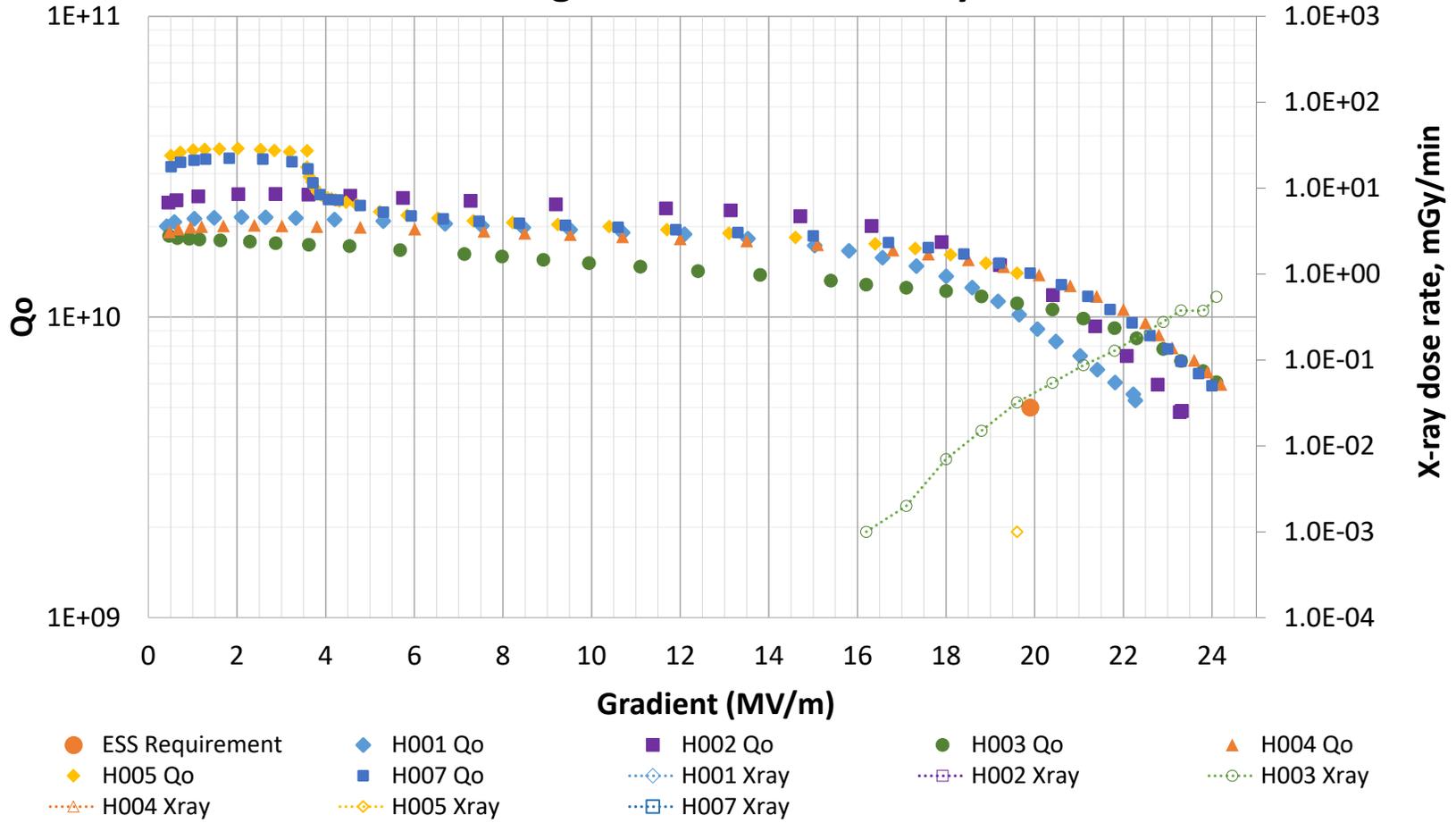
### H005 and H007:

- H007 specification achieved
- H005 hard quench at 19.8 MV/m
  - Radiation observed



# Dressed Production and Pre-Series Cavity Tests

## DESY ESS High-Beta Dressed Cavity Results



### H005 and H007:

- H007 specification achieved
- H005 hard quench at 19.8 MV/m
  - Radiation observed

### Pre-series and Production cavities:

- H003 radiation observed after He jacket installation and additional BCP
- H008 and H009 on test at present
  - High radiation levels observed

# Summary and Discussion

## Summary

- Pre-series cavities all met gradient and  $Q_0$  performance
  - No issues with Q disease witnessed
- Radiation levels observed on H002 (HPR issue) and H004
- ⇒ BCP process qualified with 4 pre-series cavities
- Production cavities released
- Statistical sample low!
- ⇒ Reliant on the experience and capability of the vendor
- Testing of production cavities just commencing

## Discussion

- PIP-II – Plan to have only 2 pre-series cavities
- ⇒ Qualification of processes more difficult (Electro-polishing and N-doping)
- Manufacturing process/capability needs to be reviewed as soon as possible
- Need to fully understand knowledge and experience gained from the prototype cavities